

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED




RB751V-40-MS

Product specification

Features

- Small surface mounting type
- Low reverse current and low forward voltage
- High reliability

Reference News

PINNING		Marking						
	<table border="1"> <thead> <tr> <th>PIN</th> <th>DESCRIPTION</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>Cathode</td> </tr> <tr> <td>2</td> <td>Anode</td> </tr> </tbody> </table>	PIN	DESCRIPTION	1	Cathode	2	Anode	
PIN	DESCRIPTION							
1	Cathode							
2	Anode							
 SOD-323								

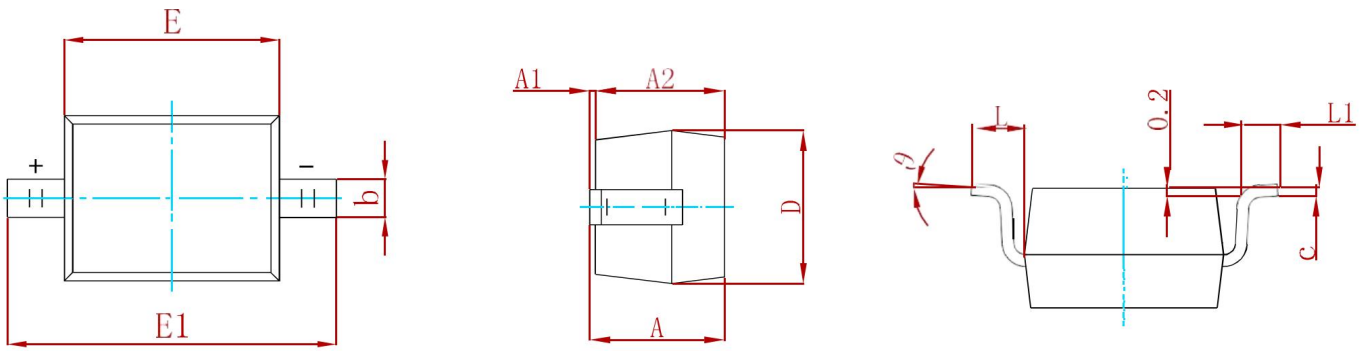
Absolute Maximum Ratings (Ta = 25°C)

Parameter	Symbol	Value	Unit
Peak Reverse Voltage	V _{RM}	40	V
Reverse Voltage	V _R	30	V
Mean Rectifying Current	I _o	30	mA
Peak Forward Surge Current (60 Hz for 1 Cyc .)	I _{FSM}	200	mA
Junction Temperature	T _j	125	°C
Storage Temperature Range	T _{stg}	- 40 to + 125	°C

Characteristics at Ta = 25°C

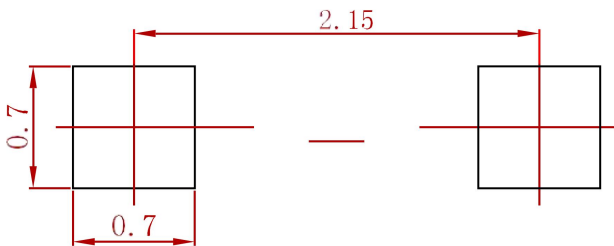
Parameter	Symbol	Typ.	Max.	Unit
Forward Voltage at I _F = 1 mA	V _F	-	0.37	V
Reverse Current at V _R = 30 V	I _R	-	0.5	μA
Capacitance Between Terminals at V _R = 1 V, f = 1 MHz	C _T	2	-	pF

PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min.	Max
A		1.000		0.039
A1	0.000	0.100	0.000	0.004
A2	0.800	0.900	0.031	0.035
b	0.250	0.350	0.010	0.014
C	0.080	0.150	0.003	0.006
D	1.200	1.400	0.047	0.055
E	1.600	1.800	0.063	0.071
E1	2.550	2.750	0.100	0.108
L	0.475 REF		0.019 REF	
L1	0.250	0.400	0.010	0.016
θ	0°	8°	0°	8°

Suggested Pad Layout



Note:

1. Controlling dimension: in millimeters.
2. General tolerance: ±0.05mm.
3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RB751V-40-MS	SOD-323	3000

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